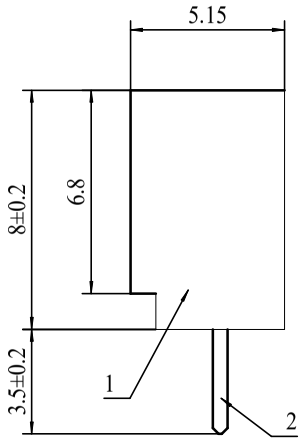
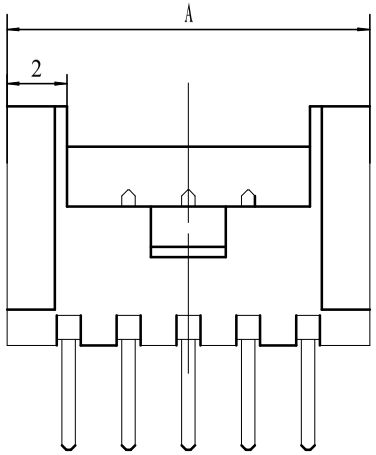
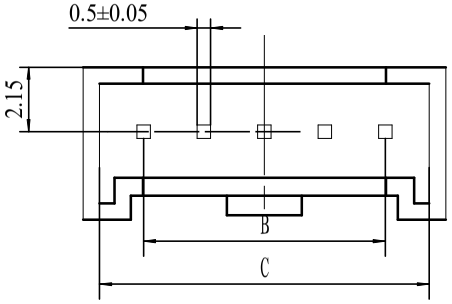
REV.	EC#	DESCRIPTION	DATE	DRAWN	CHECK	APPROVED
1.00		初版发行	2020-8-28	瞿寿坤	胡海萍	胡海萍





15P	32.0	28.0	30.9
14P	30.0	26.0	28.9
13P	28.0	24.0	26.9
12P	26.0	22.0	24.9
11P	24.0	20.0	22.9
10P	22.0	18.0	20.9
9P	20.0	16.0	18.9
8P	18.0	14.0	16.9
7P	16.0	12.0	14.9
6P	14.0	10.0	12.9
5P	12.0	8.0	10.9
4P	10.0	6.0	8.9
3P	8.0	4.0	6.9
2P	6.0	2.0	4.9
MUMBER OF PINS	DIM.A	DIM.B	DIM.C



技术要求:

1) 材质:见附表;
2) 电镀:见附表;
3) 塑件表面平整、光洁、无毛刺、气泡、烧焦、变形、浇口无拉伤、多料或缺料等不良现象;
4) 端子表面无氧化、电镀不良等现象。

适应基板厚度: 1.2mm¯1.6mm

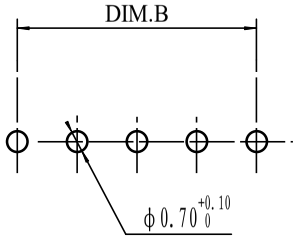
温度范围: -25℃¯85℃

额定电压: 250V AC/DC

额定电流: 1A

绝缘电阻: ⩾1000MΩ

耐 压: 800V AC/minute



PCB LAYOUT

GENERAL TOLERANCES			
DIM	TOL	DIM	DEG
X.		X°.	±3.00°
X.X	±0.35	X.X°	±2.00°
X.XX	±0.25	X.XX°	±1.00°
X.XXX	±0.15	X.XXX°	

NO.	NAME	Q'TY	DESCRIPTION
2	PIN	n PCS	材质:黄铜,电镀:镀亮锡60u"MIN
1	Housing	1 PCS	材质:PA66, 颜色:本色

深圳市虹成电子有限公司

DRAW :	瞿寿坤	2020-8-28	TITLE: WAFER 2.OHYA 立式 DIP	DRAW NAME: HC-HY2.0-6A-M	
DESIGN:	瞿寿坤	2020-8-28			
CHECK:	胡海萍	2020-8-28	SERIES: 1501 SERIES	DRAW NO.	
APPROVED	胡海萍	2020-8-28	P/N:	UNIT: mm	SHEET: 1/1
CUSTOMER DRAWING			REV. 1.00	SCALE N/A	